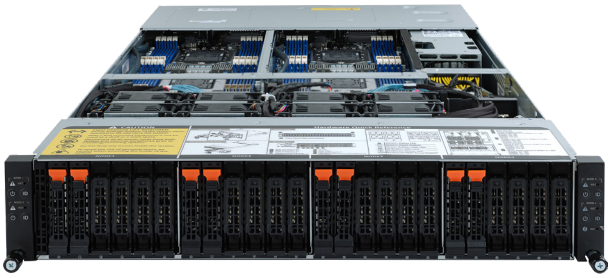
GIGABYTE™

H262-Z63

High Density Server - DP 2U 4 Nodes Server

AMD EPYC



Features

- 2U - 4 nodes rear access server system
- Dual AMD EPYC™ 7003 Series processors
- 8-Channel RDIMM/LRDIMM DDR4 per processor, 64 x DIMMs
- 8 x 1Gb/s LAN ports (Intel® I350-AM2)
- 4 x Dedicated management ports
- 1 x CMC global management port
- 8 x 2.5" NVMe hot-swappable SSD bays
- 8 x M.2 with PCIe Gen3 x4 interface
- 8 x Low profile PCIe Gen4 x16 expansion slots
- 4 x OCP 2.0 Gen3 x16 mezzanine slots
- Aspeed® AST2500 remote management controller
- 2+0 2200W (240V) 80 PLUS Platinum power supply

Specification

Dimensions	2U 4 Nodes - Rear access (W440 x H87.5 x D840 mm)
Motherboard	MZ62-HD0 Rev. 3.0
CPU	AMD EPYC™ 7003 Series processors Dual processors, 7nm technology, cTDP up to 240W Up to 64-core, 128 threads per processor Total 8 x Socket SP3, TDP up to 200W Compatible with AMD EPYC™ 7002 Series processors
Chipset	System on Chip
Memory	8-Channel DDR4 memory, total 64 x DIMM slots RDIMM/LRDIMM modules up to 128GB supported 3DS RDIMM/LRDIMM modules up to 256GB supported Memory speed: Up to 3200 MHz
LAN	8 x 1GbE LAN ports (1 x Intel® I350-AM2) 4 x Dedicated management ports 1 x 10/100/1000 CMC global management port
Video	Integrated in Aspeed® AST2500 2D Video Graphic Adapter with PCIe bus interface 1920x1200@60Hz 32bpp, DDR4 SDRAM
Storage	8 x 2.5" NVMe hot-swappable SSD bays All storage bays are compatible with SATA devices
Expansion Slots	8 x Low profile half-length slots with PCIe x16 (Gen4 x16) 4 x OCP 2.0 mezzanine slot with PCIe Gen3 x16 bandwidth 8 x M.2 slots (PCIe Gen3 x4, M-key)
Internal I/O	Per node: 2 x M.2 slots, 1 x COM header, 1 x TPM header, 1 x BMC SGPIO header, 1 x JTAG BMC header, 1 x PLD header, 1 x Clear CMOS jumper, 1 x IPMB connector
Front I/O	-
Rear I/O	Total: 8 x USB 3.0, 4 x VGA, 8 x RJ45, 4 x MLAN, 1 x CMC LAN

Backplane I/O	8 x ports; Speed and bandwidth: SATA 6Gb/s or SAS 12Gb/s or PCIe Gen3 x4 per port
TPM	1 x TPM header with SPI interface Optional TPM2.0 kit: CTM010
Power Supply	2+0 2200W (240V) 80 PLUS Platinum power supply
System Management	Aspeed® AST2500 management controller GIGABYTE Management Console (AMI MegaRAC SP-X)
OS Compatibility	Windows Server 2016 / 2019 RHEL 8.3 (x64) or later SLES 12 SP5 (x64) / 15 SP2 (x64) or later Ubuntu 18.04.5 LTS (x64) / 20.04 LTS (x64) or later VMware ESXi 6.7 Update3 P03 / 7.0 Update1 or later Citrix Hypervisor 8.2.0 or later
Weight	Net Weight: 28 kg / Gross Weight: 50 kg
System Fans	8 x 80x80x38mm (16,300rpm)
Operating Properties	Operating temperature: 10°C to 35°C Operating humidity: 8-80% (non-condensing) Non-operating temperature: -40°C to 60°C Non-operating humidity: 20%-95% (non-condensing)
Packaging Content	1 x H262-Z63, 8 x CPU heatsinks, 1 x Rail kit
Reference Numbers	Barebone package: 6NH262Z63MR-00 Rev. A00 - Motherboard: 9MZ62HD0NR-00 Rev. 3.0 - Rail kit: 25HB2-AN6103-K0R - CPU heatsink: 25ST1-44320H-A0R/25ST1-44320I-A0R - Back plane board: 9CBPH080NR-00 - NVMe M.2 extension card for Slot_R: 9CMTP04RNR-00 (optional) - Power Supply: 25EP0-222003-D0S - C19 type power cord 125V/15A (US): 25CP1-018000-Q0R (optional) - C19 type power cord 250V/16A (EU): 25CP3-01830H-Q0R (optional) - C19 type power cord 250V/15A (US): 25CP1-018300-Q0R (optional) - Ring topology kit: 6NH262Z65SR-00-100 (optional)